

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

1 Application Serial No. .... 09/961,114  
2 Filing Date ..... 09/20/2001  
3 Inventor..... Perino et al.  
4 Group Art Unit ..... 2833  
5 Examiner ..... Figueroa, Felix O  
Attorney's Docket No. ..... RB1-035USC3  
Title: ..... Chip Socket Assembly and Chip File Assembly for Semiconductor Chips

10/D  
T. Steptoe  
7-16-03

**AMENDMENT AND RESPONSE TO OFFICE ACTION**  
**DATED APRIL 16, 2003**

9 To: Box Non-Fee Amendment  
Commissioner for Patents  
10 P.O. Box 1450  
11 Alexandria, VA 22313-1450

FAX RECEIVED

JUL 10 2003

12 From: Kenneth Paley  
Customer No. 29150  
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14 421 W Riverside Ave Suite 500  
Spokane, WA 99201

TECHNOLOGY CENTER 2800

15 Dear Sir:

16 This is a reply under 37 CFR § 1.114 to a final Office Action mailed April  
17 16, 2003, for the above identified application. Claims 68, 70-75, 77, 79-83 and 85-  
18 88 are pending and have been rejected. Claims 89-90 have been withdrawn.

19 Claims 68, 79, 87, and 88 are herein canceled. Claims 74, 77, 80, 81, 85, 86  
20 are herein amended. Claims 91-97 are herein added.

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07/16/2003 TSTEP 01 FC:1202 54.00 DA  
22 The Applicants request that the Examiner enter the following amendments,  
and consider the following remarks.